

In the Claims:

Please Amend Claim 1 as follows:

1. (AMENDED) A method to form passivation openings that prevent protective tape residue in the manufacture of an integrated circuit device comprising:

providing a semiconductor substrate;

5        depositing a passivation layer overlying said semiconductor substrate;

6        depositing an organic photoresist layer overlying said passivation layer;

10        patterning said organic photoresist layer to expose said passivation layer in areas where said passivation openings are planned;

reflowing said organic photoresist layer to create gradually sloping sidewalls on said organic photoresist layer;

15        thereafter etching through said passivation layer not covered by organic photoresist layer to form said passivation openings with gradually sloping sidewalls wherein said etching does not etch said organic photoresist layer;